

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	IS&R	L1	5957	(257/81,98,433,724,777).CCLS.	US-PGPUB; USPAT; EPO; DERWENT	2006/07/23 14:49
2	BRS	L10	13	9 and @ad<"20030226"	US-PGPUB; USPAT; EPO; DERWENT	2006/07/23 14:59
3	BRS	L11	9	10 and (solder "solder layer" "wetting layer")	US-PGPUB; USPAT; EPO; DERWENT	2006/07/23 14:59
4	BRS	L12	9	11 and (solder "solder layer" "wetting layer")	US-PGPUB; USPAT; EPO; DERWENT	2006/07/23 15:00
5	BRS	L2	4200	1 and (chip die chips dies)	US-PGPUB; USPAT; EPO; DERWENT	2006/07/23 14:50
6	BRS	L3	1194	2 and (mirror reflector reflective reflecting)	US-PGPUB; USPAT; EPO; DERWENT	2006/07/23 14:51
7	BRS	L8	134	3 and (mirror reflector reflective reflecting) near5 (conductive conductor "conductive material")	US-PGPUB; USPAT; EPO; DERWENT	2006/07/23 14:59
8	BRS	L9	24	8 and (barrier "barrier layer")	US-PGPUB; USPAT; EPO; DERWENT	2006/07/23 14:59

	<b>Document ID</b>	<b>Kind Codes</b>	<b>Source</b>	<b>Issue Date</b>	<b>Pages</b>
1	US 20030015721 A1		US- PGPUB	20030123	17
2	US 20010004534 A1		US- PGPUB	20010621	11
3	US 7075112 B2		USPAT	20060711	27
4	US 6797987 B2		USPAT	20040928	12
5	US 6740906 B2		USPAT	20040525	19
6	US 6222207 B1		USPAT	20010424	11
7	US 5956605 A		USPAT	19990921	14
8	US 5917202 A		USPAT	19990629	8
9	US 5698866 A		USPAT	19971216	16